VIN
3V to 11.5V

S+
S-

-VOUT

ON
OFF

VIN
GND
PG
SS/TR
FB
VOUT
PAD
U1
TPS82130SILR

Built on PWR720 Rev B
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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